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Dated: January 30, 2002

Signature: 

(William Smith)

1765
Docket No.: NANO 3.0-007
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Beetz et al.

Application No.: 10/001,358

Group Art Unit: N/A

Filed: October 24, 2001

Examiner: Not Yet Assigned

For: PROCESS FOR PRODUCING
MACROSCOPIC CAVITIES BENEATH THE
SURFACE OF A SILICON WAFER

Commissioner for Patents
Washington, DC 20231

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INFORMATION DISCLOSURE STATEMENT

Dear Sir:

It is respectfully requested that the references listed on the enclosed form be made of record and considered with respect to the above-referenced U.S. patent application. A copy of each reference is enclosed. Submission of the present Information Disclosure Statement should not be taken as an admission that the cited references are legally available prior art or that the same are pertinent or material.

In the event that any fee is due in connection with the present Information Disclosure Statement, the Commissioner is hereby authorized to charge the same to our Deposit Account No. 12-1095.

Dated: January 30, 2002

Respectfully submitted,

By 
William Smith

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